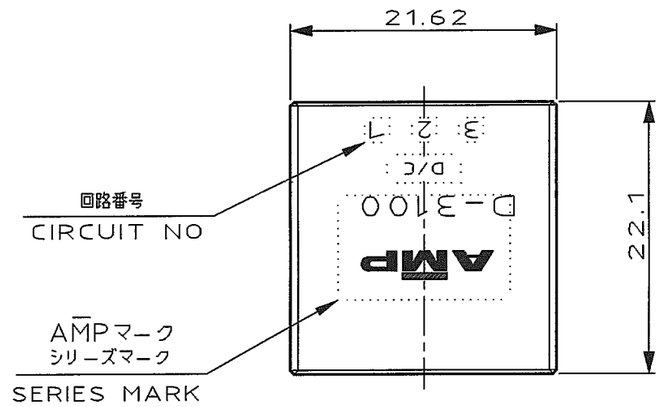
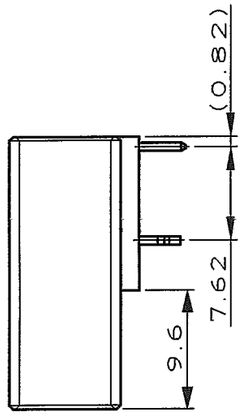
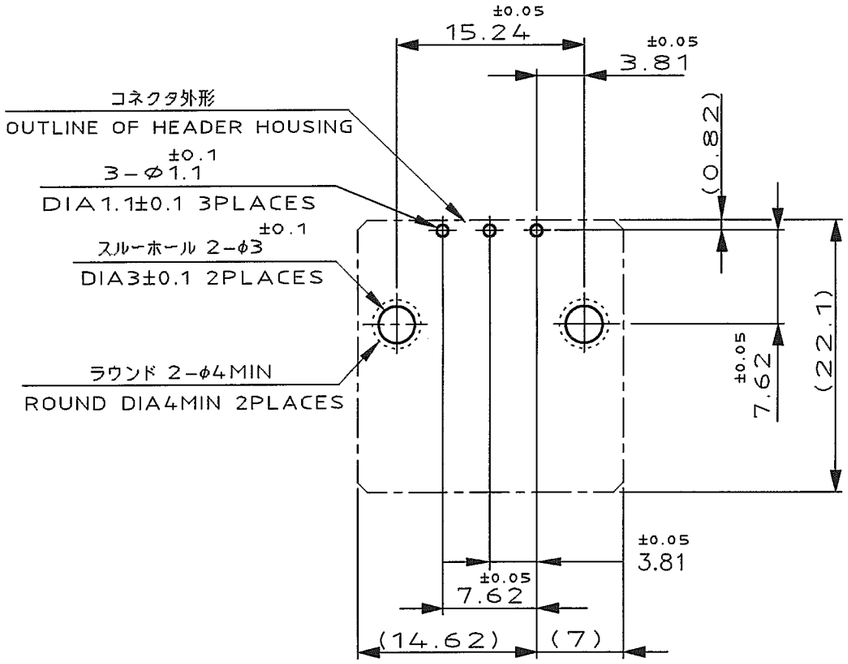
NUMBER 178293

3rd ANGLE PROJECTION

METRIC



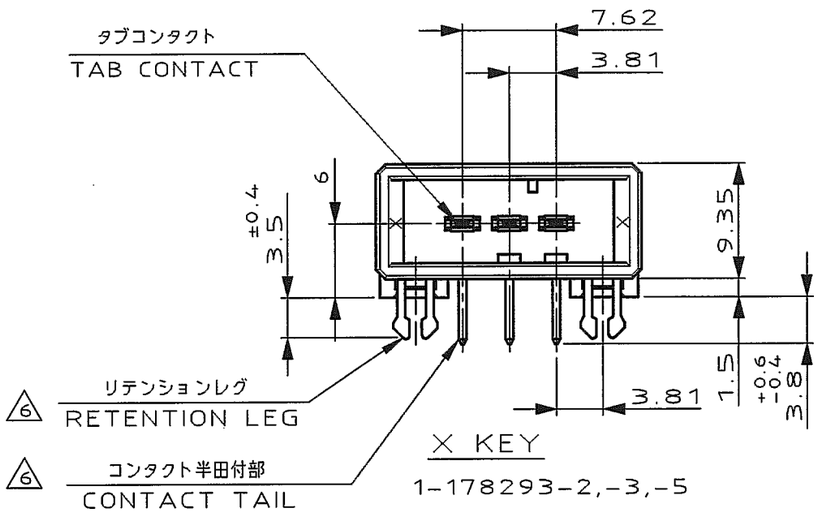




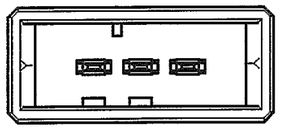
推奨基板取付け穴寸法

PC 基板厚:1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS:1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)



X KEY
1-178293-2,-3,-5



Y KEY
2-178293-2,-3,-5

NOTES

1. MATERIAL:HOUSING:GLASS FILED THERMO PLASTIC,POLYESTER
   CONTACT:COPPER ALLOY
   RETENTION LEG:COPPER ALLOY
2. FINISH(CONTACT AREA):0.38μmMIN GOLD PLATING OVER Ni PLATING
3. FINISH(CONTACT AREA):0.76μmMIN GOLD PLATING OVER Ni PLATING
4. FINISH(CONTACT AREA):2.0 μmMIN TIN PLATED OVER NICKEL
5. ~~FINISH(RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL~~
6. FINISH(RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

1. 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
   コンタクト: 銅合金
   リテンションレグ: 銅合金
2. めっき: コンタクト: 全面Ni下地 接触部:0.38μm MIN金めっき
3. めっき: コンタクト: 全面Ni下地 接触部:0.76μm MIN金めっき
4. めっき: コンタクト: 全面Ni下地 接触部:2.0 μm MINスズめっき
5. ~~めっき: リテンションレグとコンタクト半田付部 : ニッケル下地の上に半田めっき~~
6. めっき: リテンションレグとコンタクト半田付部 : ニッケル下地の上にスズめっき

6	4	1,2-178293-5
6	3	1,2-178293-3
6	2	1,2-178293-2
(FINISH)		製品番号 (PART NO.)

LTR	REVISION RECORD	DR	CHK	DATE
C1	REVISED PER ECO-11-005030	RK	HMR	14APR 11

TE Connectivity

WIRE RANGE	mm²(AWG -)
INSULATION DIA	- mm
MATERIAL	SEE NOTE 注記参照
FINISH	SEE NOTE 注記参照
DR.	20/MAR/'95 K.IKEDA
DE.	20/MAR/'95 K.IKEDA
CHK.	23.MAR'92 S.MANABE
APP.	23.MAR'92 S.MANABE

NAME: 3 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC 3100

一般公差 (GENERAL TOLERANCE): 10以下 ±0.3; 10を超え30以下 ±0.4; 30を超え100以下 ±0.5; 角度 ±3°

SIZE A3 | LOC J | NUMBER C-178293 | SCALE 2-1 | REV. C1 | SHEET 1 OF 1

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST

(CUSTOMER DRAWING) 顧客用図面